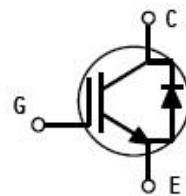


## Insulated Gate Bipolar Transistor

### General Description:

Using DongHai's proprietary Trench design and advanced FS technology, the 650V FS IGBT offers superior conduction and switching performances, high avalanche ruggedness and easy parallel operation.

<b>V<sub>CES</sub></b>	<b>650</b>	<b>V</b>
<b>I<sub>C</sub></b>	<b>20</b>	<b>A</b>
<b>P<sub>tot</sub> T<sub>C</sub>=25°C)</b>	<b>96</b>	<b>W</b>
<b>V<sub>CE(SAT)</sub></b>	<b>1.9</b>	<b>V</b>


**TO-220F**


### Features:

- FS Trench Technology, Positive temperature coefficient
- Low saturation voltage: V<sub>CE(sat)</sub>, typ = 1.9V  
@ I<sub>C</sub> = 20A and T<sub>C</sub> = 25°C
- Extremely enhanced avalanche capability

### Applications:

Motor Control、PFC、UPS...

### Absolute Maximum Ratings (T<sub>C</sub> = 25°C unless otherwise specified):

Symbol	Parameter	Rating	Units
V <sub>CES</sub>	Collector-Emitter Voltage	650	V
V <sub>GES</sub>	Gate- Emitter Voltage	±20	V
I <sub>C</sub>	Collector Current	40	A
	Collector Current @TC = 100 °C	20	A
I <sub>CM</sub> <sup>a1</sup>	Pulsed Collector Current	60	A
I <sub>F</sub>	Diode Continuous Forward Current @TC = 100 °C	20	A
I <sub>FM</sub>	Diode Maximum Forward Current	60	A
P <sub>D</sub>	Power Dissipation @ TC = 25°C	96	W
T <sub>J</sub> , T <sub>stg</sub>	Operating Junction and Storage Temperature Range	-55 to +150	°C
T <sub>L</sub>	Maximum Temperature for Soldering	270L	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
R <sub>θJC</sub>	Thermal Resistance, Junction to case for IGBT	--	4.8	°C/W
R <sub>θJC</sub>	Thermal Resistance, Junction to case for Diode	--	6.9	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient	--	62.5	°C/W

**Electrical Characteristics of the IGBT ( Tc= 25°C unless otherwise specified):**

<b>OFF Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
BV <sub>CES</sub>	Collector-Emitter Breakdown Voltage	V <sub>GE</sub> =0V,I <sub>CE</sub> =250uA	650	--	--	V
I <sub>CES</sub>	Collector-Emitter Leakage Current	V <sub>GE</sub> =0V V <sub>CE</sub> =650V	--	--	1.0	mA
I <sub>GES(F)</sub>	Gate to Emitter Forward Leakage	V <sub>GE</sub> =+20V	--	--	+250	nA
I <sub>GES(R)</sub>	Gate to Source Reverse Leakage	V <sub>GE</sub> =-20V	--	--	-250	nA

<b>ON Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	I <sub>c</sub> =20A,V <sub>GE</sub> =15V	--	1.9	2.4	V
V <sub>GE(TH)</sub>	Gate Threshold Voltage	I <sub>c</sub> =250uA,V <sub>CE</sub> =V <sub>GE</sub>	4.5	5.7	7	V
Pulse width tp≤300μs,δ≤2%						

<b>Dynamic Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
C <sub>ies</sub>	Input Capacitance	V <sub>CE</sub> =25V,V <sub>GE</sub> =0V f=1MHz	--	1095	--	pF
C <sub>oes</sub>	Output Capacitance		--	60	--	
C <sub>res</sub>	Reverse Transfer Capacitance		--	32	--	

<b>Resistive Switching Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>CE</sub> =400V,I <sub>c</sub> =15A V <sub>GE</sub> =15V, R <sub>g</sub> =10Ω Inductive Load , Ta=25°C	--	30	--	ns
tr	Rise Time		--	30	--	
t <sub>d(OFF)</sub>	Turn-Off Delay Time		--	45	--	
t <sub>f</sub>	Fall Time		--	34	--	mJ
Eon	Turn-On Switching Loss		--	0.6	--	
Eoff	Turn-Off Switching Loss		--	0.19	--	
Ets	Total Switching Loss		--	0.79	--	
Q <sub>g</sub>	Total Gate Charge	V <sub>CE</sub> =400V,I <sub>c</sub> =15A V <sub>GE</sub> =15V	--	59	--	nC

**Electrical Characteristics of the DIODE ( Tc= 25°C unless otherwise specified):**

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> =10A	--	1.4	--	V
T <sub>rr</sub>	Reverse Recovery Time		--	47	--	ns
I <sub>rr</sub>	Diode Peak Reverse Recovery Current	I <sub>F</sub> =10A di/dt=100A/uS	--	7.5	--	A
Q <sub>rr</sub>	Reverse Recovery Charge		--	176	--	nC
Pulse width t <sub>tp</sub> ≤300μs,δ≤2%						

<sup>a1</sup>: Repetitive rating; pulse width limited by maximum junction temperature

## Characteristics Curve

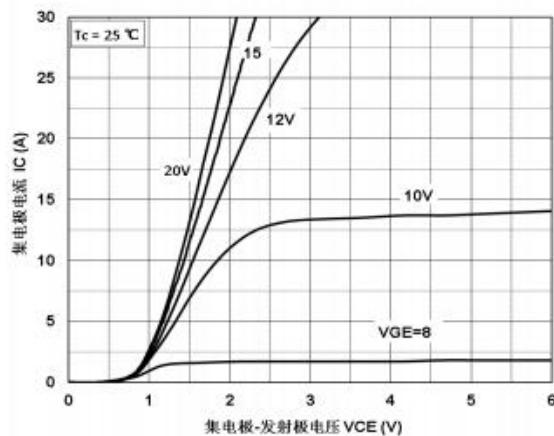


图 1. 输出特性

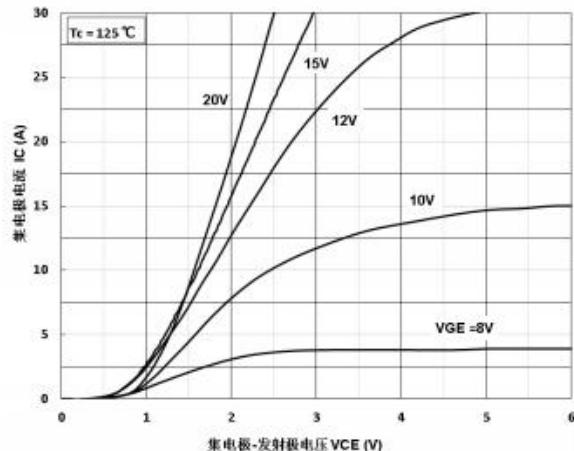


图 2. 输出特性

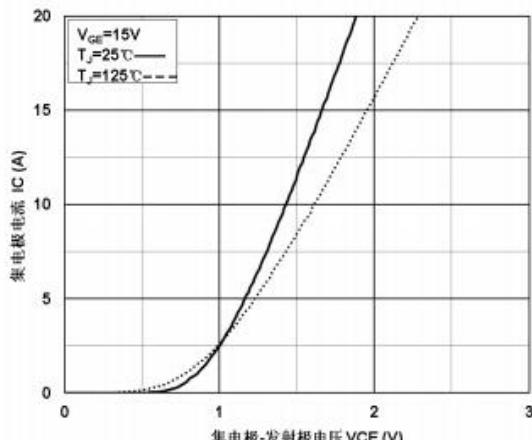


图 3. 饱和压降特性

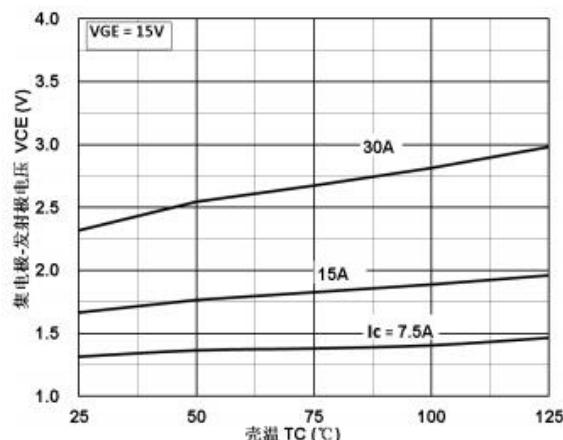


图 4. 饱和压降-温度特性

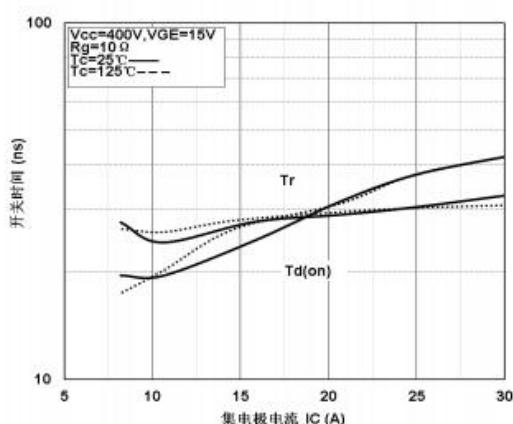


图 5. 开通时间-I<sub>C</sub> 特性

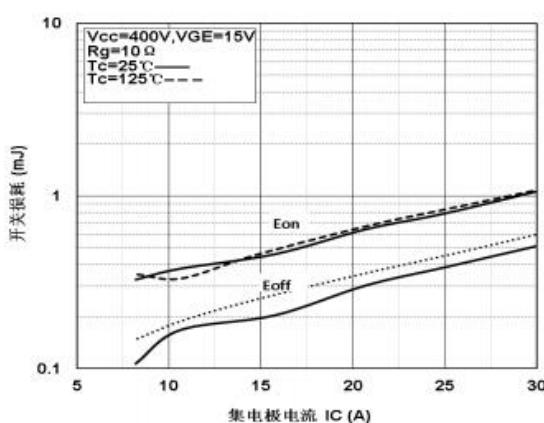


图 6. 开关损耗-I<sub>C</sub> 特性

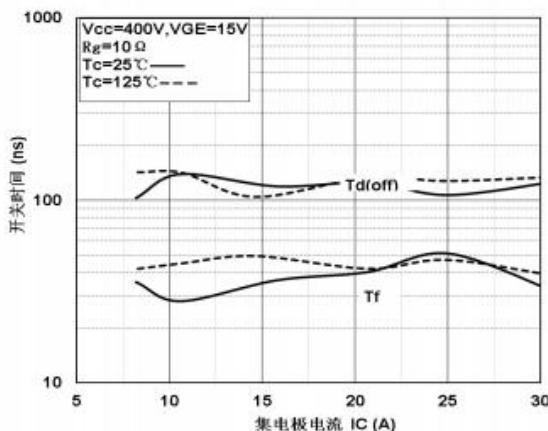


图 7. 关断时间— $I_c$  特性

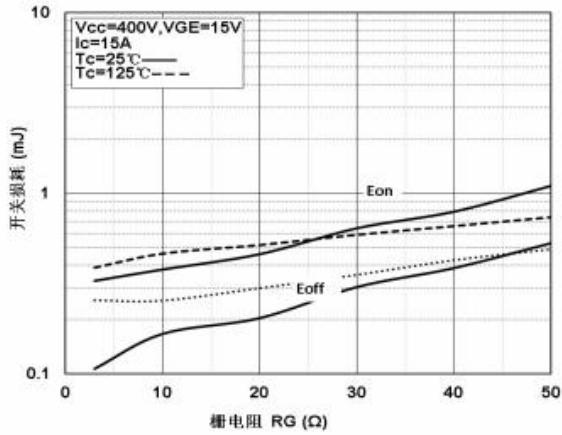


图 8. 开关损耗— $R_g$  特性

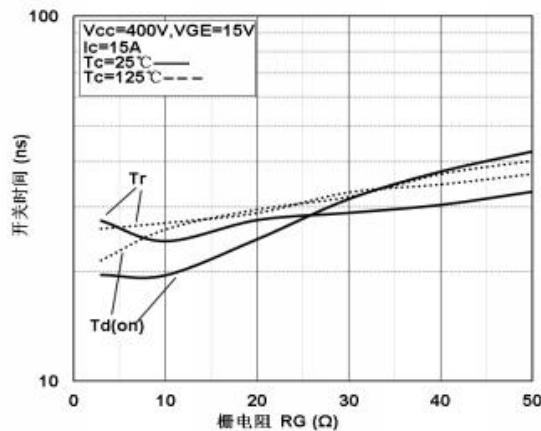
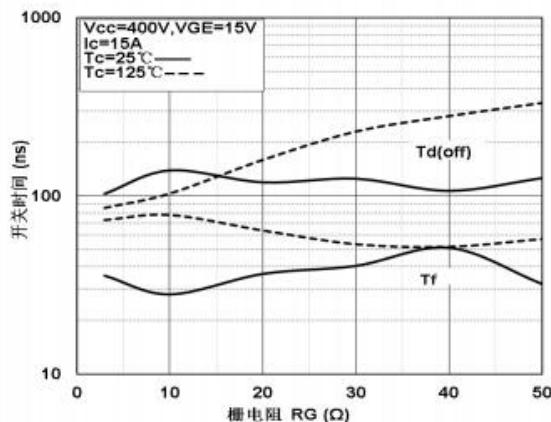


图 10. 关断时间— $R_g$  特性

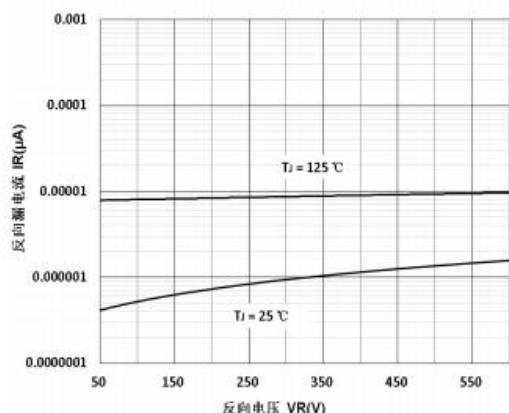


图 11. 二极管的反向漏电特性

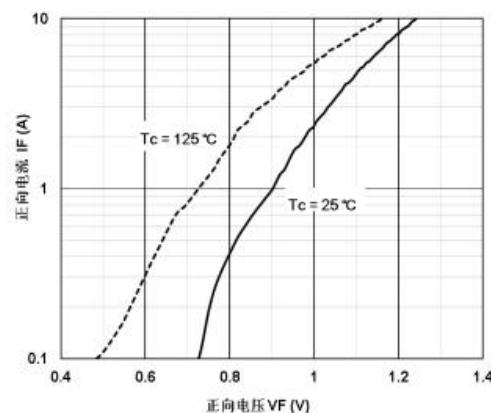
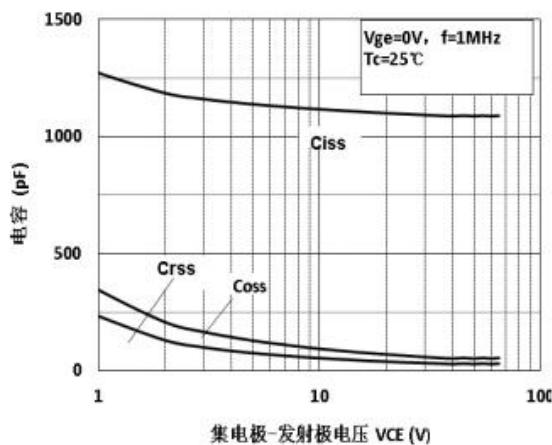
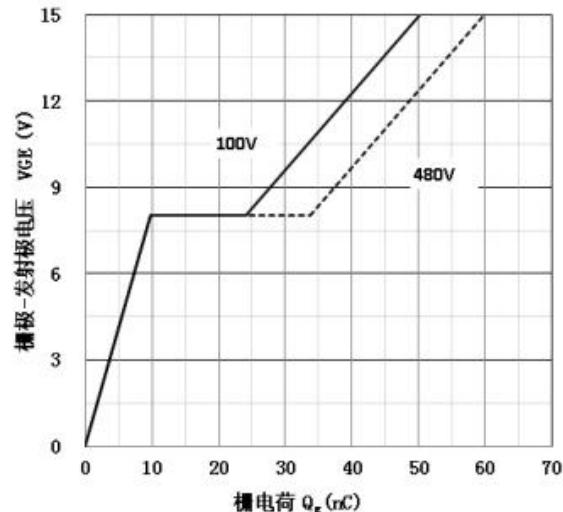
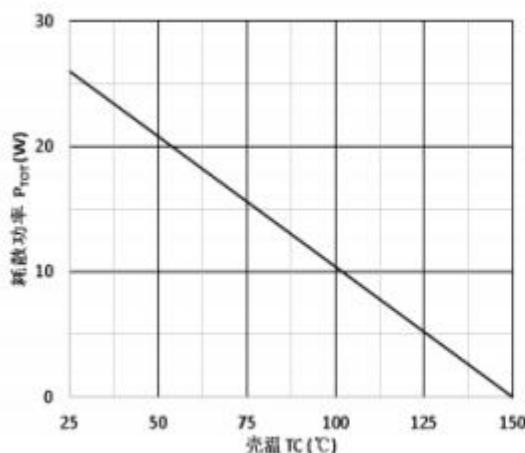
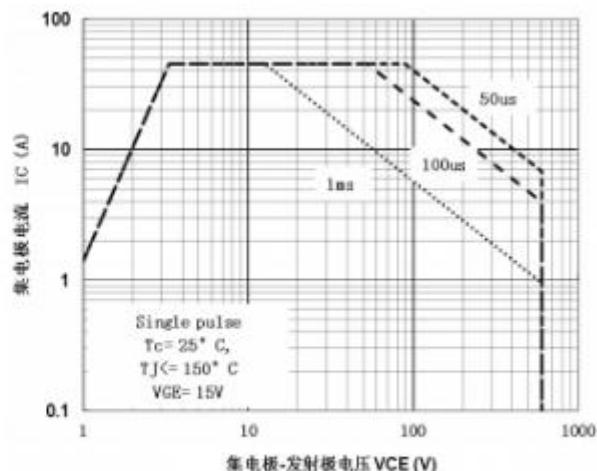
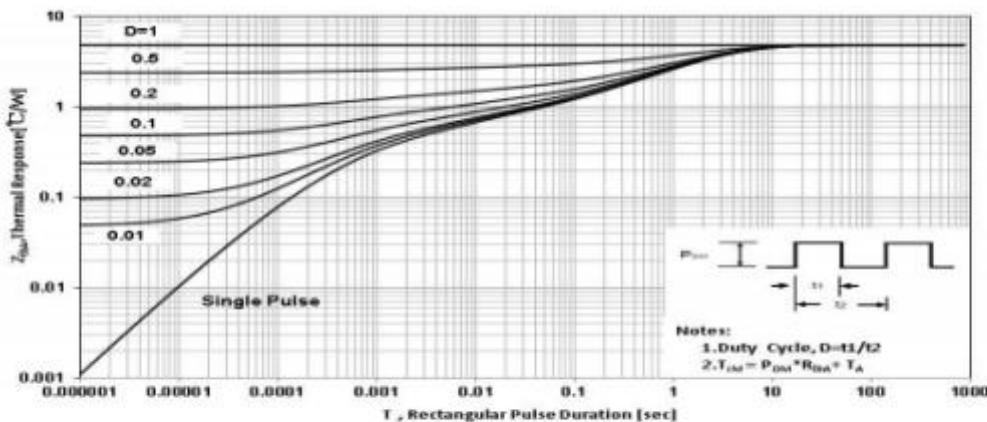
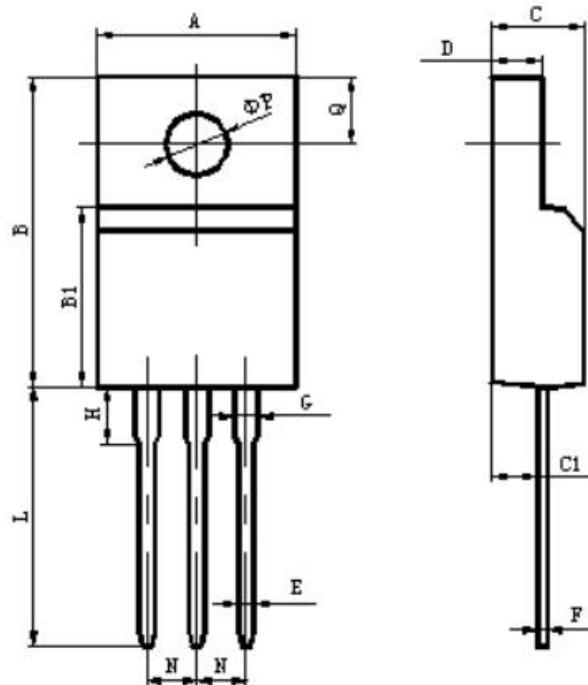


图 12. 二极管的正向压降特性


**图 13. 电容特性**

**图 14. 栅电荷特性**

**图 15. 耗散功率-壳温 Tc 特性 (TO-220F)**

**图 16. 安全工作区 (TO-220F)**

**图 17. IGBT 瞬态热阻特性 (TO-220F)**

**外形图 (TO-220F):**


Items	Values(mm)	
	MIN	MAX
A	9.60	10.4
B	15.4	16.2
B1	8.90	9.50
C	4.30	4.90
C1	2.10	3.00
D	2.40	3.00
E	0.60	1.00
F	0.30	0.60
G	1.12	1.42
H	3.40	3.80
	1.60	2.90
L*	12.0	14.0
N	2.34	2.74
Q	3.15	3.55
P	2.90	3.30



DHG20T65D